



RELIABILITY REPORT  
FOR  
MAX1721EUT+  
PLASTIC ENCAPSULATED DEVICES

February 8, 2010

**MAXIM INTEGRATED PRODUCTS**

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<b>Approved by</b>
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## Conclusion

The MAX1721EUT+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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## I. Device Description

### A. General

The ultra-small MAX1719/MAX1720/MAX1721 monolithic, CMOS charge-pump inverters accept input voltages ranging from +1.5V to +5.5V. The MAX1720 operates at 12kHz, and the MAX1719/MAX1721 operate at 125kHz. High efficiency, small external components, and logic-controlled shutdown make these devices ideal for both battery-powered and board-level voltage conversion applications. Oscillator control circuitry and four power MOSFET switches are included on-chip. A typical MAX1719/MAX1720/MAX1721 application is generating a -5V supply from a +5V logic supply to power analog circuitry. All three parts come in a 6-pin SOT23 package and can deliver a continuous 25mA output current. For pin-compatible SOT23 switched-capacitor voltage inverters without shutdown (5-pin SOT23), see the MAX828/MAX829 and MAX870/MAX871 data sheets. For applications requiring more power, the MAX860/MAX861 deliver up to 50mA. For regulated outputs (up to  $-2 \times V_{IN}$ ), refer to the MAX868. The MAX860/MAX861 and MAX868 are available in space-saving  $\mu$ MAX® packages.

## II. Manufacturing Information

A. Description/Function:	SOT23, Switched-Capacitor Voltage Inverters with Shutdown
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	March 31, 1999

## III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1101-0115
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115°C/W
K. Single Layer Theta Jc:	80°C/W

## IV. Die Information

A. Dimensions:	35 X 57 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{6.211}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 45.5 \times 10^{-9}$$
$$\lambda = 45.5 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.04 @ 25C and 0.69 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The PX87-1 die type has been found to have all pins able to withstand a transient pulse of:

HBM: +/-2500 V per JESD22-A114

CDM: +/-750 V Per JESD22-C101

Latch-Up testing has shown that this device withstands a current of +/-250 ma.

**Table 1**  
Reliability Evaluation Test Results

**MAX1721EUT+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	2
<b>Moisture Testing</b> (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data